Texas Instruments

Bill of Materials

TI DESIGNS

TIDEP0019

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	P2	DNP	pin_array_3x2				pin_array_3x2	
2	1	U2	DNP	256-kb Serial CMOS EEPROM	OnSemi	CAT24C256		SO8E	
3	1	C1	DNP	1u				SM0805	
4	2	R1, ⊠ 2	DNP	1k5				SM0805	
5	3	R3,R4,R5	DNP	4k75				SM0805	
6	1	J1	DNP	PIN_ARRAY_2X2				PIN_ARRAY_2X2	
7	1	U1		BEAGLEBONE	ТІ			BEAGLEBONE	
8	2	RV1, ⊠ V2	2k Ohm	РОТ	Vishay / Sfernice	TS53YL202MR10		POT_CMS	
9	2	R9, ⊠ 7	1k Ohm		KOA Speer	RK73H2ATTD1001F		SM0805	
10	5	D5,D7,D6,D1,D2		BI_LED	Kingbright	AM23ESGC		SOT23	
11	3	SW1,SW2,SW3		SW_PUSH_SMALL	TE Connectivity / Alcos	5-1437565-0		SW_PUSH_SMALL	
12	1	G***	DNP	LOGO				LOGO	
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